FBHA Series
Chip Ferrite Bead High Current Type
Size 1206

FBHA
FBHA120
FBHA1206-1
FBHA1206-151-
FBHA1206-301-102
FBHA1206-471-102R
FBHA1206-501-302R
FBHA1206-601-202R
FBHA1206-601-302R

FEATURES

I_R refering to 40K self-heating above ambie

APPLICATION

-

Dimensions: [mm]

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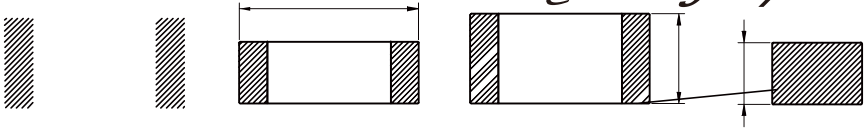
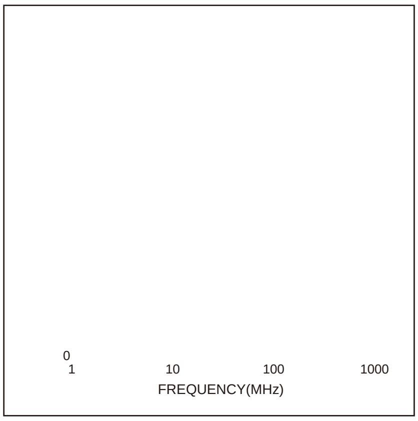
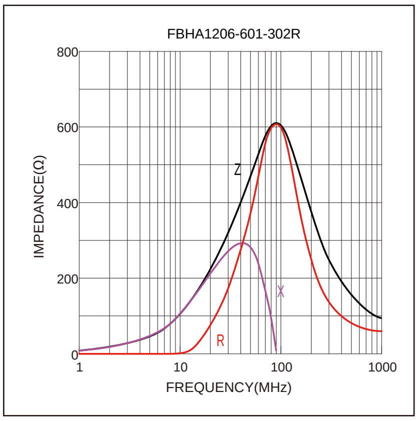
Land Pattern: [mm]



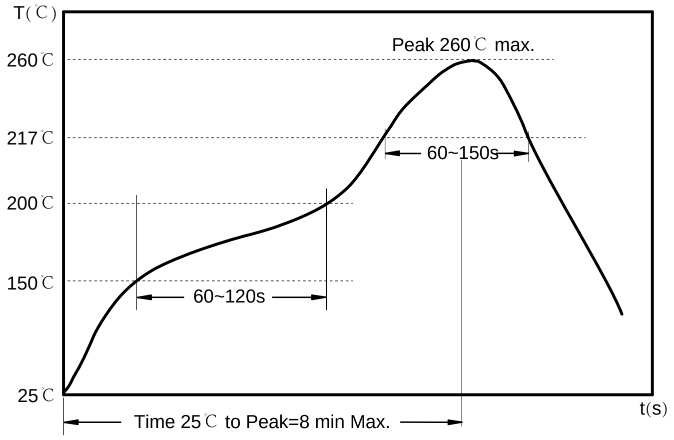
Electrical Properties:

Typical Electrical Characteristics:




FBHA1206-601-302R
800
600
400
200
0
IMPEDANCE(Ω)
Z
X
R
1
10
100
1000
FREQUENCY(MHz)

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

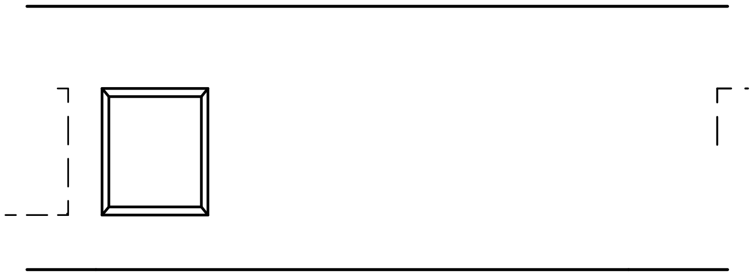
Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Allowed Reflow time: 3x max.

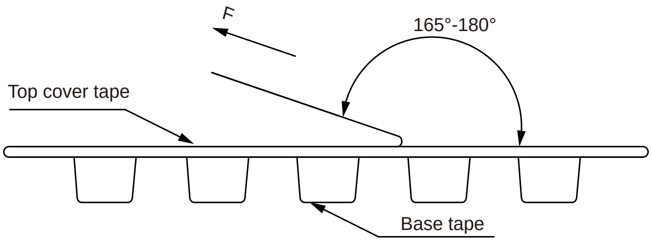
Packaging Information:

Tape Dimension:



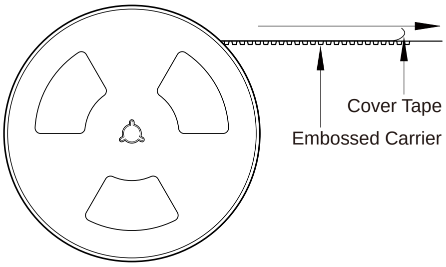
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
FBHA1206	1.75 ± 0.1	3.35 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	4.0 ± 0.1	8.0 ± 0.3	1.25 ± 0.1	1.75 ± 0.1	0.23 ± 0.05

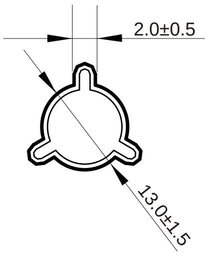
Peel force of top cover tape:

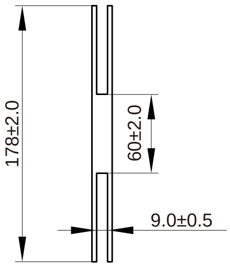


The peel force of top cover tape shall be between 0.14 to 0.58 N

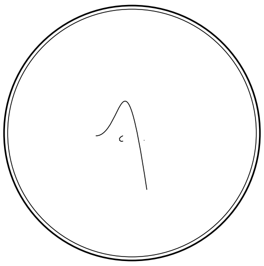
Reel Dimension: [mm]







Packaging Quantity:



3000 Pcs/Reel   5 Reel /Inner box(15K Pcs)   8 Inner box/Carton box(120K Pcs)

Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.